TOSHIBA Photocoupler GaAs IRed & Photo-Transistor

# **TLP570,TLP571**

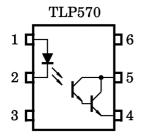
Programmable Controllers
AC / DC-Input Module
Solid State Relay

The TOSHIBA TLP570 and TLP571 consist of a darlington connected photo–transistor optically coupled to a gallium arsenide infrared emitting diode in a six lead plastic DIP package.

TLP570 is no-base internal connection for high-EMI environments.

- Collector-emitter voltage: 35V (min.)
- Current transfer ratio: 1000% (min.)
- Isolation voltage: 2500Vrms (min.)
- UL recognized: UL1577, file no. E67349

#### Pin Configurations (top view)

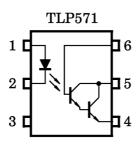


1 : ANODE 2 : CATHODE

3: NC

4 : EMITTER 5 : COLLECTOR

6: NC



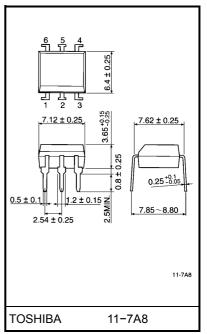
1 : ANODE 2 : CATHODE

3: NC

4 : EMITTER 5 : COLLECTOR

6: BASE

Unit in mm





#### **Maximum Ratings (Ta = 25°C)**

	Characteristic	Symbol	Rating	Unit
	Forward current	l <sub>F</sub>	70	mA
	Forward current derating (Ta ≥ 25°C)	ΔI <sub>F</sub> / °C	-0.7	mA / °C
E	Peak forward current (100µs pulse, 100pps)	I <sub>FP</sub>	1	Α
	Reverse voltage	V <sub>R</sub>	5	V
	Junction temperature	Tj	125	°C
	Collector-emitter voltage	V <sub>CEO</sub>	35	V
	Collector-base voltage (TLP571)	V <sub>CBO</sub>	80	V
	Emitter-collector voltage	V <sub>ECO</sub>	7	V
ctor	Emitter-base voltage (TLP571)	V <sub>EBO</sub>	7	V
Detector	Collector current	I <sub>C</sub>	150	mA
	Power dissipation	PC	150	mW
	Power dissipation derating (Ta ≥ 25°C)	ΔP <sub>C</sub> / °C	-1.5	mW / °C
	Junction temperature	Tj	125	°C
Stor	rage temperature range	T <sub>stg</sub>	<b>−55~125</b>	°C
Оре	erating temperature range	T <sub>opr</sub>	<b>−55~100</b>	°C
Lea	d soldering temperature (10s)	T <sub>sold</sub>	260	°C
Tota	al package power dissipation	P <sub>T</sub>	250	mW
Tota	al package power dissipation derating (Ta ≥ 25°C)	ΔP <sub>T</sub> / °C	-2.5	mW / °C
Isola	ation voltage (AC, 1 min., R.H.≤ 60%) (Note 1)	BVS	2500	V <sub>rms</sub>

(Note 1) Device considered a two terminal: Pins1, 2 and 3 shorted together and pins 4, 5 and 6 shorted together.

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#### **Recommends Operating Conditions**

Characteristic	Symbol	Min.	Тур.	Max.	Unit
Supply voltage	V <sub>CC</sub>	_	5	24	V
Forward current	lF	_	16	25	mA
Collector current	IC	_	_	50	mA
Operating temperature	T <sub>opr</sub>	-25	_	85	°C



### Individual Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min.	Тур.	Max.	Unit
	Forward voltage	$V_{F}$	I <sub>F</sub> = 10 mA	1.0	1.15	1.3	V
LED	Reverse current	I <sub>R</sub>	V <sub>R</sub> = 5 V	_	_	10	μA
	Capacitance	C <sub>T</sub>	V = 0, f = 1 MHz	_	30	_	pF
	Collector–emitter breakdown voltage	V <sub>(BR)CEO</sub>	I <sub>C</sub> = 1 mA	35	_	_	V
Detector	Emitter-collector breakdown voltage	V <sub>(BR)ECO</sub>	I <sub>E</sub> = 0.1 mA	7	_	_	V
	Collector-base breakdown voltage (TLP571)	V <sub>(BR)CBO</sub>	I <sub>C</sub> = 0.1 mA	80	_	_	V
	Emitter-base breakdown voltage (TLP571)	V <sub>(BR)EBO</sub>	I <sub>E</sub> = 0.1 mA	7	_	_	V
	Collector dark current	I <sub>CEO</sub>	V <sub>CE</sub> = 24 V	_	10	200	nA
			V <sub>CE</sub> = 24 V, Ta = 85°C	_	_	300	μA
	Collector dark current (TLP571)	I <sub>CER</sub>	V <sub>CE</sub> = 24 V, Ta = 85°C R <sub>BE</sub> = 10 MΩ	_	0.5	10	μA
	Collector dark current (TLP571)	I <sub>CBO</sub>	V <sub>CB</sub> = 10 V	_	0.01	_	nA
	DC forward current gain (TLP571)	h <sub>FE</sub>	V <sub>CE</sub> = 5 V, I <sub>C</sub> = 10 mA	_	50k	_	_
	Capacitance (collector to emitter)	C <sub>CE</sub>	V = 0, f = 1 MHz	_	10	_	pF

### Coupled Electrical Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	MIn.	Тур.	Max.	Unit
Current transfer ratio	I <sub>C</sub> / I <sub>F</sub>	I <sub>F</sub> = 1 mA, V <sub>CE</sub> = 1 V	1000	2000	_	%
Saturated CTR	I <sub>C</sub> / I <sub>F (sat)</sub>	I <sub>F</sub> = 10 mA, V <sub>CE</sub> = 1 V	500	_	_	%
Base photo-current (TLP571)	I <sub>PB</sub>	I <sub>F</sub> = 1 mA, V <sub>CB</sub> = 1 V	_	2	_	μΑ
Collector-emitter	V ( )	I <sub>C</sub> = 10 mA, I <sub>F</sub> = 1 mA	_	_	1.0	V
saturation voltage	V <sub>CE</sub> (sat)	I <sub>C</sub> = 100 mA, I <sub>F</sub> = 10 mA	0.3	_	1.2	V



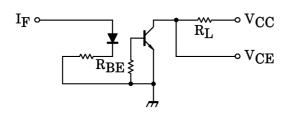
## Isolation Characteristics (Ta = 25°C)

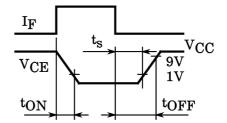
Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Capacitance (input to output)	CS	V <sub>S</sub> = 0, f = 1 MHz	-	0.8	١	pF
Isolation resistance	R <sub>S</sub>	V <sub>S</sub> = 500 V, R.H. ≤ 60%	5×10 <sup>10</sup>	10 <sup>14</sup>	-	Ω
		AC, 1 minute	2500	_	1	V <sub>rms</sub>
Isolation voltage	$BV_S$	AC, 1 second, in oil	_	5000	_	v rms
		DC, 1 minute, in oil	_	5000	_	V <sub>dc</sub>

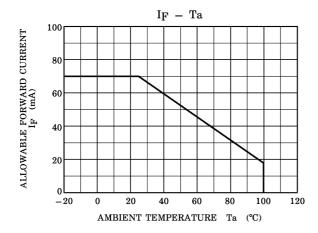
### **Switching Characteristics (Ta = 25°C)**

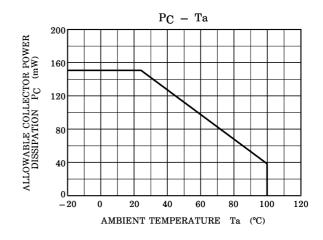
Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Rise time	t <sub>r</sub>	$V_{CC}$ = 10 V $I_{C}$ = 10 mA $R_{L}$ = 100 $\Omega$	_	40	_	
Fall time	t <sub>f</sub>		_	30	_	116
Turn-on time	t <sub>ON</sub>		_	45	_	μs
Turn-off time	toff		_	35	_	
Turn-on time	t <sub>ON</sub>	$R_L = 180\Omega$ (Fig.1)	_	5	_	
Storage time	ts	R <sub>BE</sub> = open	_	20	_	μs
Turn-off time	t <sub>OFF</sub>	$V_{CC}^{} = 10 \text{ V}, I_F = 10 \text{ mA}$	_	100	_	
Turn-on time	t <sub>ON</sub>	$R_L = 180\Omega$ (Fig.1)	_	5	_	
Storage time	ts	$R_{BE} = 10M\Omega (TLP571)$	_	15	_	μs
Turn-off time	t <sub>OFF</sub>	$V_{CC} = 10 \text{ V, I}_{F} = 10 \text{ mA}$	_	60	_	

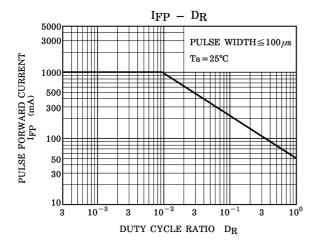
Fig. 1 Switching time test circuit

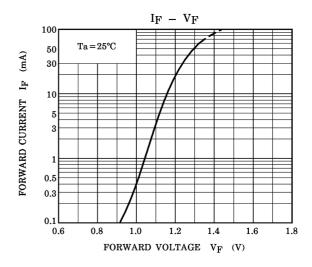


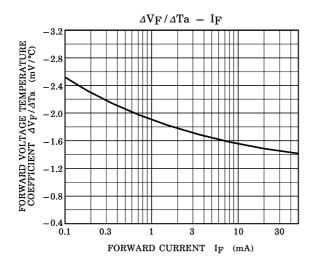


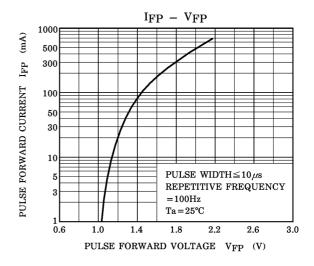


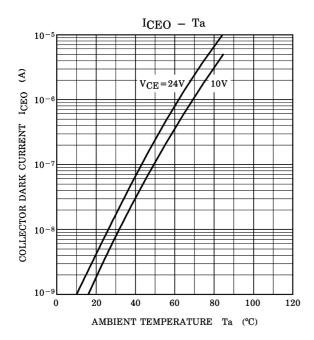


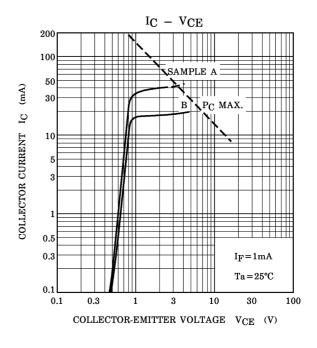


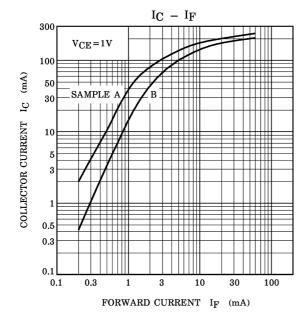


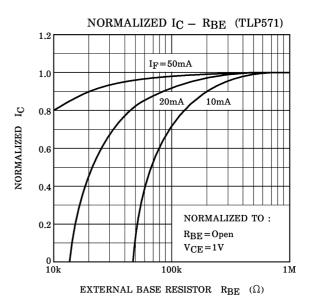




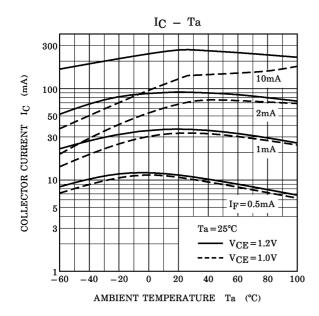


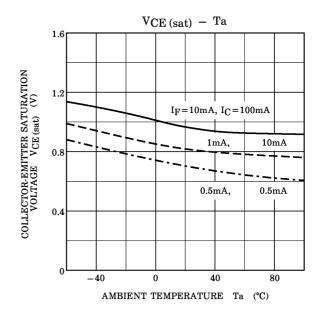


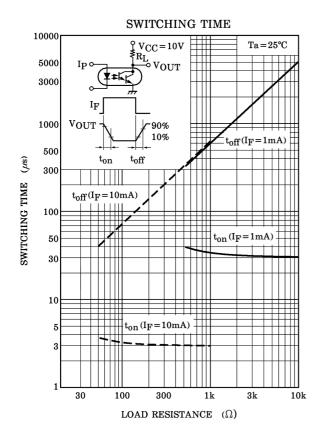


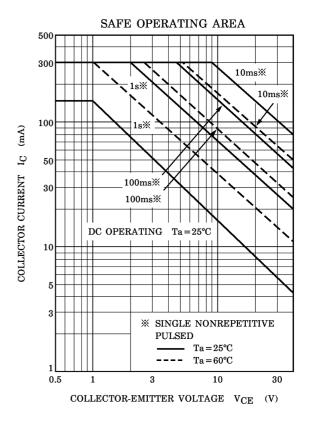


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